

1 7. (Amended) A capillary bonding tool according to claim 1, wherein
2 the coating is at least one of i) a polymer, ii) an Alumina, iii) Si₃N₄ iv) silica v) a
3 combination of 12% silica and 88% Alumina, and vi) a Diamond like coating (DLC).

1 8. (Amended) A bonding tool for bonding a wire to a substrate, the
2 bonding tool having a body and a working tip coupled to one end of the body, and
3 comprising:

4 an orifice extending along a longitudinal axis of the body and the working
5 tip; and

6 a coating disposed over at least a portion of a surface of the orifice,
7 wherein the coating is a polymer disposed along an interior surface of the
8 orifice and one of i) an Alumina, ii) Si₃N₄, iii) silica, iv) a combination of 12% silica
9 and 88% Alumina, and v) a Diamond like coating (DLC) disposed along an exterior
10 portion of the orifice.

1 10. (Amended) A bonding tool for bonding a wire to a substrate, the
2 bonding tool having a body and a working tip coupled to one end of the body, and
3 comprising:

4 an orifice extending along a longitudinal axis of the body and the working
5 tip; and

6 a coating disposed over at least a portion of a surface of the orifice,
7 wherein the coating has a substantially uniform thickness of up to about
8 2.0 microns.

Please add claim 28 as follows:

1 28. (Newly Added) A bonding tool for bonding a wire to a substrate,
2 the bonding tool having a body and a working tip coupled to one end of the body, and
3 comprising:

4 an orifice extending along a longitudinal axis of the body and the working
5 tip; and
6 a non-conductive coating disposed over at least a portion of a surface of
7 the orifice.